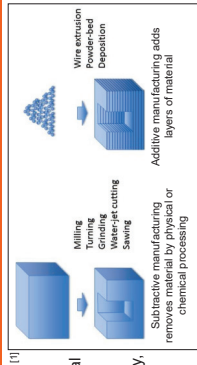




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## Introduction

- Additive manufacturing utilizes metal nanoparticle ink for the printing of microelectronic devices.
- Since this technology is in its infancy, only a few metal nanoparticle inks are commercially available.
- Nickel and copper nanoparticle inks were developed and will be printed using an Optomec-200 Aerosol Jet Printer.
- Surface Acoustic Wave (SAW) devices will be printed on a piezoelectric substrate to show the viability of the nanoparticle ink.
- The devices are to be characterized, optimized, and utilized in the pursuit of high temperature sensors that can withstand neutron bombardment.

## Objectives

- Synthesize metal nanoparticles
- Make an ink out of the nanoparticles
- Print the ink using an Aerosol Jet Printer
- Test printed sensors for viability

## Methods

- Focused on nickel(II) acetate and copper(II) sulfate
- Use of the **Polyol Method** for nanoparticle synthesis.<sup>[2]</sup>
- Nanoparticles were capped with polyvinylpyrrolidone (PVP) and reduced using sodium borohydride (NaBH<sub>4</sub>)<sup>[3]</sup>
- Nanoparticles were isolated from ethylene glycol using an ultra-centrifuge set at 28k rpm.
- Then they were washed two-three times with ethanol to remove any remaining organic material

## Results

- The nickel nanoparticles were made into an ink and printed with an Aerosol Jet Printer.
- The ink was a mixture of nickel nanoparticles, ethylene glycol, water, and glycerol.<sup>[4]</sup>
- The printed line widths were between 20um and 100um.
- A simulated print of the inter-digitated transducers (IDT) was conducted.
- Copper nanoparticles were synthesized according to the same synthesis procedure as the nickel nanoparticles.

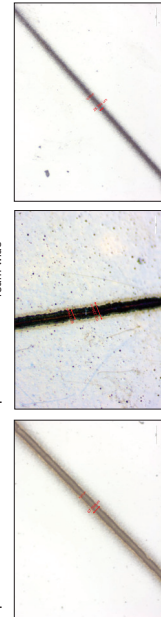
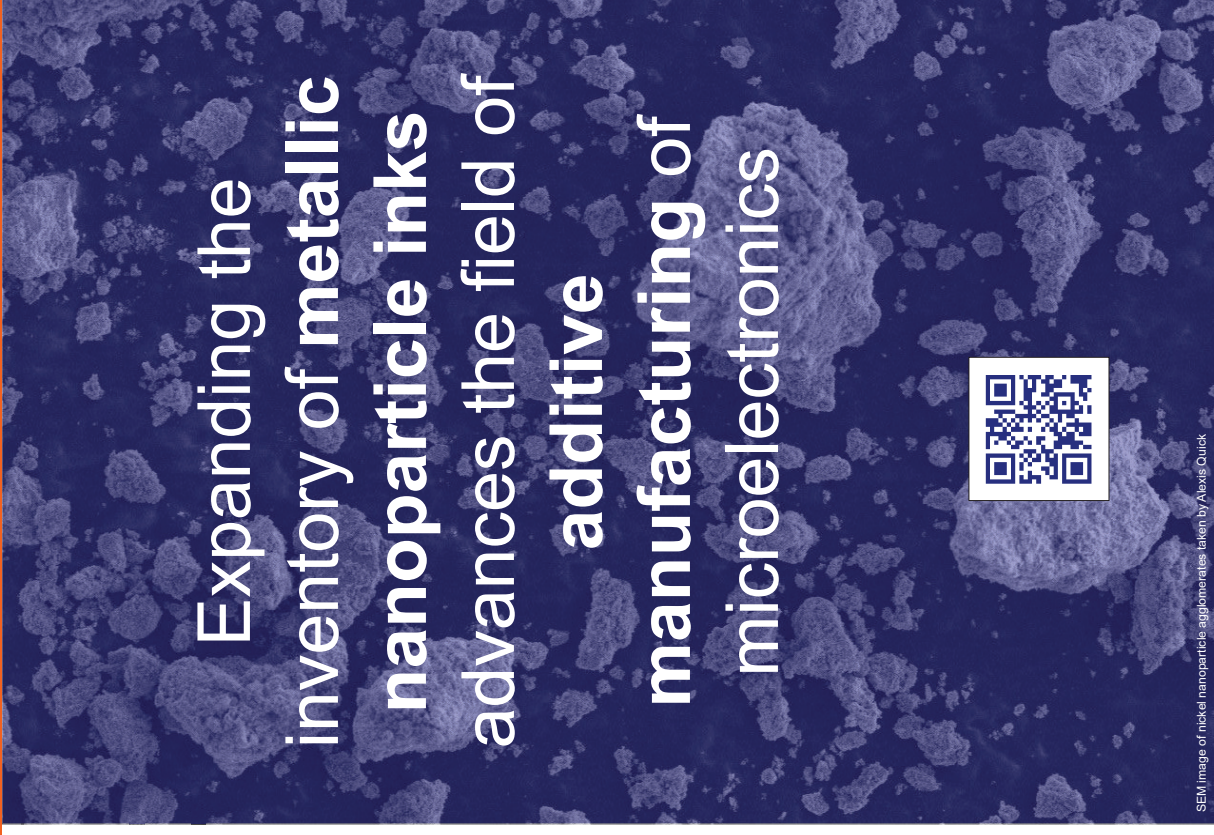


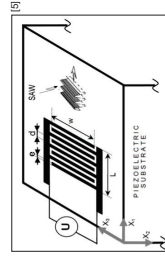
Figure 2-4: Lines of nickel nanoparticle ink printed by an Aerosol Jet Printer ranging from 25um to 60um in width



# Expanding the inventory of metallic nanoparticle inks advances the field of additive manufacturing of microelectronics



SEM image of nickel nanoparticle agglomerates taken by Alexis Quick

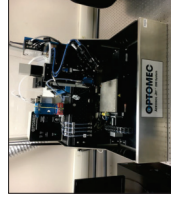


## SAW Devices

- Inter-digitated transducers are printed on a piezoelectric substrate<sup>[5]</sup>
- An oscillating voltage is applied to the device to produce surface acoustic wave
- The piezoelectric substrate propagates longitudinal waves across the surface

**Surface Acoustic Waves (SAW)** are sound waves that travel parallel to the surface of the substrate. They are preferred for applications involving indirect contact or high-temperature measurements. **Piezoelectric effect** is the ability of a material to generate an electric charge in response to applied mechanical stress. Piezoelectric sensors have a simple structure, fast response time in high-temperatures, and are easy to integrate into any system.<sup>[7]</sup>

## Aerosol Jet Printer



- Advantages:
- Maskless (Direct Transfer)
  - Efficient
  - Cost-effective
  - Underdeveloped technique
  - Few commercially available inks

## Characterization TEM, DLS, and XRD

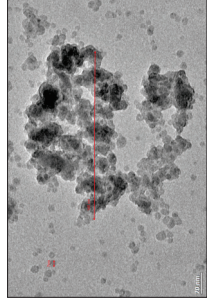


Figure 5: Transmission Electron Microscopy image of nickel nanoparticle ink featuring a 150nm agglomerate and individual 5-10nm particles

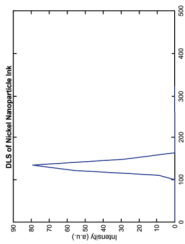


Figure 6: Dynamic Light Scattering data for nickel nanoparticle ink showing the average agglomeration size is about 140nm

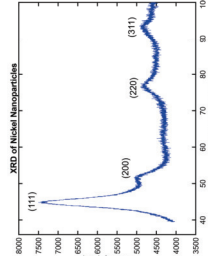


Figure 7: X-ray Diffraction pattern for nickel nanoparticles that confirmed the particles had no contamination and a crystal structure of FCC

## Future Work

- Making an ink out of the synthesized copper nanoparticles
- Optimizing the ink components for both metals
- Optimizing the printing of both metal inks
- Testing the printed SAW devices for high temperature applications

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